

P-Channel Enhancement Mode MOSFET

Feature

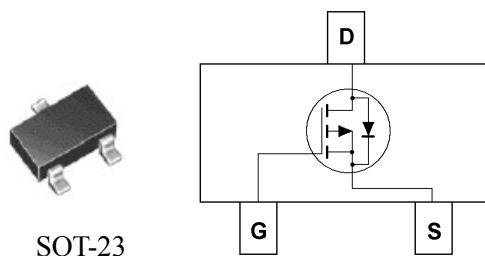
-20V/-2A, R_{DS(ON)} = 120mΩ(MAX) @V_{GS} = -4.5V.

R_{DS(ON)} = 150mΩ(MAX) @V_{GS} = -2.5V.

Super High dense cell design for extremely low R_{DS(ON)}

Reliable and Rugged

SOT-23 for Surface Mount Package



Applications

- Power Management

Portable Equipment and Battery Powered Systems.

Absolute Maximum Ratings

T_A=25°C Unless Otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _{GS}	±10	V
Drain Current-Continuous	I _D	-2	A

Electrical Characteristics

T_A=25°C Unless Otherwise noted

Parameter	Symbol	Test Conditions	Min	Typ.	Max	Units
Off Characteristics						
Drain to Source Breakdown Voltage	BVDSS	V _{GS} =0V, I _D =-250μA	-20	-	-	V
Zero-Gate Voltage Drain Current	IDSS	V _{DS} =-20V, V _{GS} =0V	-	-	-1	μA
Gate Body Leakage Current, Forward	IGSSF	V _{GS} =10V, V _{DS} =0V	-	-	100	nA
Gate Body Leakage Current, Reverse	IGSSR	V _{GS} =-10V, V _{DS} =0V	-	-	-100	nA
On Characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{GS} = V _{DS} , I _D =-250μA	-0.4	-	-1.0	V
Static Drain-source	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-2.0A	-	--	120	mΩ
On-Resistance		V _{GS} =-2.5V, I _D =-1.5A	-	--	150	mΩ
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =-1.25A	-	-	-1.2	V

Typical Characteristics

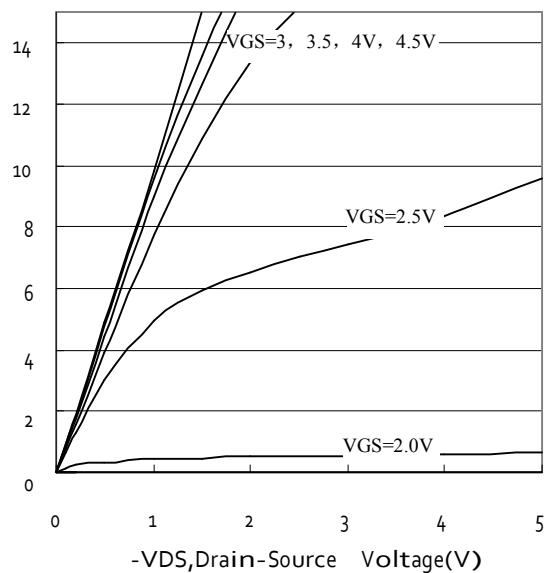


Figure 1. Output Characteristics

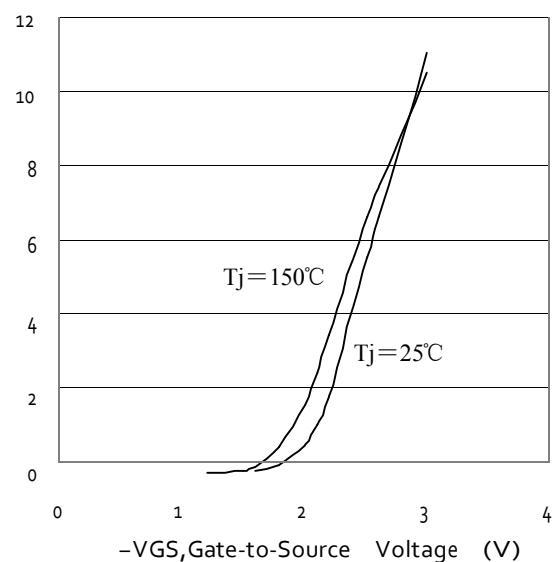


Figure 2. Transfer Characteristics

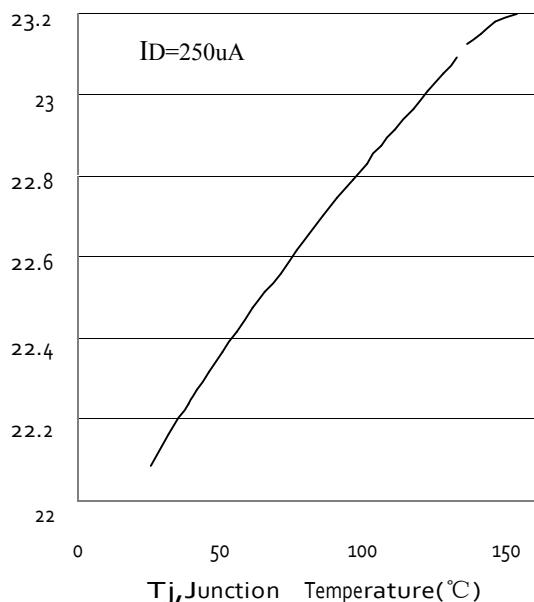


Figure 3. Breakdown Voltage Variation with Temperature

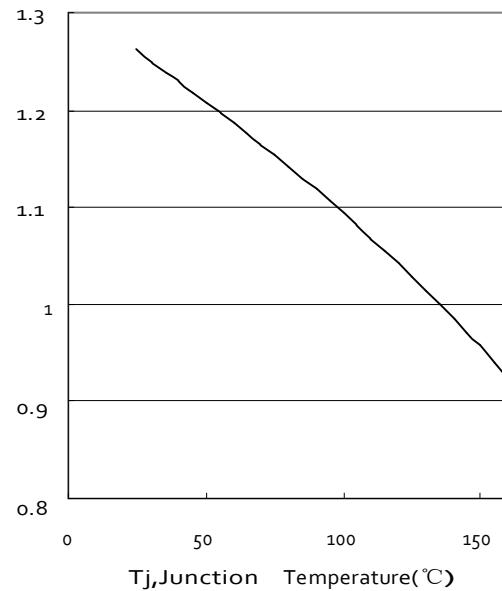


Figure 4. Gate Threshold Variation with Temperature

Typical Characteristics

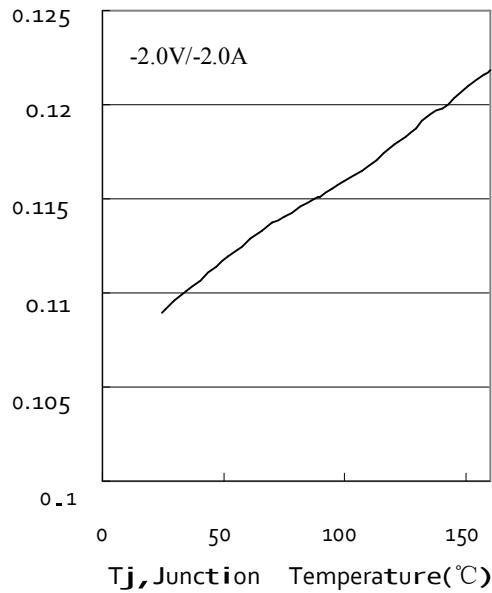


Figure 5. On-Resistance Variation with Temperature

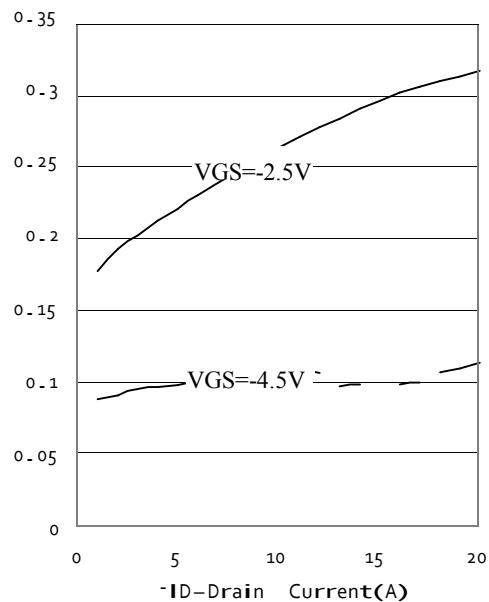


Figure 6. On-Resistance vs. Drain Current

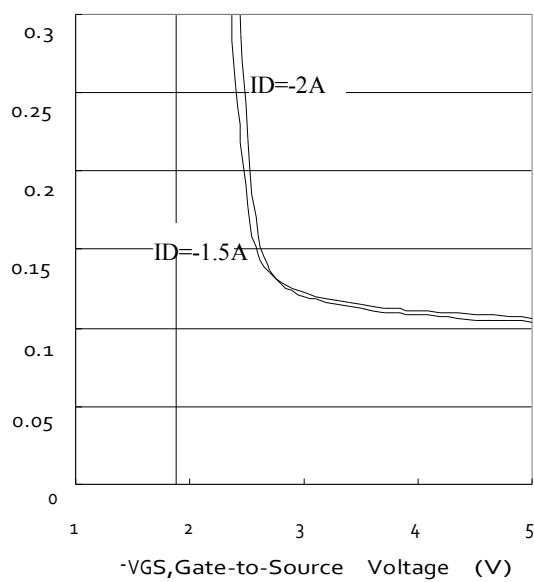


Figure 7 . On-Resistance vs. Gate-to-Source Voltage

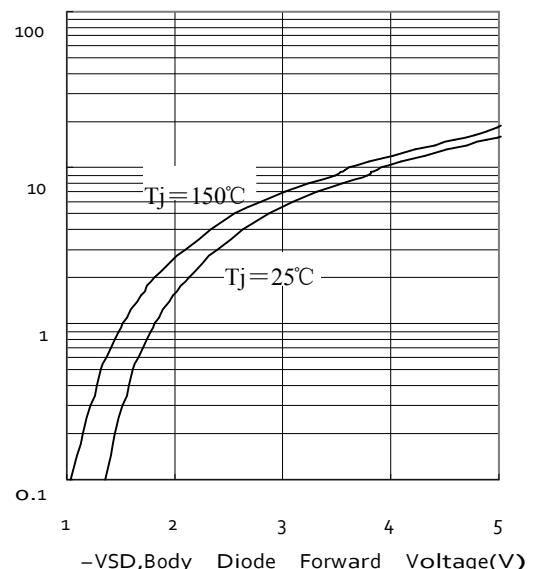


Figure 8 . Source-Drain Diode Forward

Voltage

Package Outline Dimensions (UNIT: mm)

SOT-23

